



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-08-06
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giovanni Giacobello	<b>Representative Title</b>	IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	RVW8*V795AA5	A	ZS1A	2015-08-06
Amount	UoM	Unit type	ST ECOPACK Grade	
7.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	1.80 - 1.15 - 0.8	5	gull wing	
Comment	Package: SOT 323 5LDS; MDF valid for LDK120C18R			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	RVW8*V795AA5						
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	Other inorganic materials	0.288	mg	supplier	die	Silicon (Si)	7440-21-3		0.269	mg	934028	38429	
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	13889	571	
Die				supplier	metallization	Tungsten (W)	7440-33-7		0.003	mg	10417	429	
Die				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.001	mg	3472	143	
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.007	mg	24306	1000	
Die				supplier	polymer die coating	PIXI Gamma-butyrolactone	96-48-0		0.004	mg	13889	571	
Leadframe	Copper & its alloys	2.299	mg	supplier	alloy	Copper (Cu)	7440-50-8		2.215	mg	963462	316429	
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.051	mg	22184	7286	
Leadframe				supplier	alloy	Phosphorus (P)	12185-10-3		0.001	mg	435	143	
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.003	mg	1305	429	
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.026	mg	11309	3714	
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.002	mg	870	286	
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	435	143	
Die attach	Other inorganic materials	0.024	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.016	mg	666667	2286	
Die attach				supplier	glue or tape	methylene diacrylate	42594-17-2		0.006	mg	250000	857	
Die attach				supplier	glue or tape	Dicyclopentenylxyethyl methacrylate	68586-19-6		0.001	mg	41667	143	
Die attach				supplier	glue or tape	Polymer of Polybutadiene + Anhydride	Proprietary		0.001	mg	41667	143	
Bonding wire	Precious metals	0.038	mg	supplier	wire	Copper (Cu)	7440-50-8		0.037	mg	973684	5286	
Bonding wire				supplier	wire	Palladium (Pd)	7440-05-3		0.001	mg	26316	143	
encapsulation	Other inorganic materials	4.351	mg	supplier	mold compound	Silica, vitreous	29690-82-2		3.742	mg	860032	534571	
encapsulation				supplier	mold compound	phenolic resin	25068-38-6		0.13	mg	29878	18571	
encapsulation				supplier	mold compound	epoxy resin	25068-38-6		0.252	mg	57918	36000	
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.218	mg	50103	31143	
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.009	mg	2068	1286	